

## Retifica al Capitolato Tecnico

PON "Ricerca e Innovazione 2014-2020" Avviso D.D. n. 424 del 28/02/2018 per la concessione di finanziamenti finalizzati al potenziamento di infrastrutture di ricerca, in attuazione dell'Azione II.1

PACK(PIR01\_00021)

Potenziamento Appulo Campano di KM3NeT

Fornitura di 16.000 schede di elettronica per fotomoltiplicatori da 3" e loro integrazione e coating

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Atto G.E. n. 12406 del 14.05.2020

CUP I11G18000190001

CIG Lotto1: 83215307CA

CIG Lotto2: 8321549778

## 2.2 PRODUCTION AND PCB-A TESTING

Testing for production faults is at the discretion of the manufacturer using the locally available testing equipment and is part of the assembly and supply of the PCB and can consist, amongst others, of:

- Testing of the Bare board PCB: optically and electrically;
- Testing during assembly:
  - Optical check of paste
  - Components test before soldering. The test consists in:
    - Case integrity;
    - Pin integrity and oxidation.
  - Optical assessment of solder joints

**A functional test** must be performed using a test setup provided by NIKHEF, ~3 minutes per PCB. The tester is described in "BASE03 HV Tester.pdf". In order to reduce the time needed to test all bases, NIKHEF will distribute 4 testers.

The output of the functional test will consist of different results:

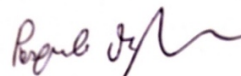
- The base is OK and ready for the assembly; the base is not OK;
- An ascii file containing all the details of the test;
- The association between the serial number printed on the PCB and the 3D-QR code mounted onto the board.

## 3.10 COATING

It is identified with the covering of the active base and the photomultiplier with tropicalised varnish **cod. RS1991496** (alternatives are possible but should be approved by KM3NeT). It should be applied in a clean and dust-free environment, and with temperature and humidity in the range ( 20-30°C) and (< 50%), respectively.

This phase must be done by immersion of the assembly up to half of the metal shielding (tolerance + - 2mm) leaving the PMT head (detector area). The drying will be done in special shelves for 24 hours at temperature range (20- 30°C).

Il Responsabile Unico del Procedimento



(dott. Pasquale Migliozi)



UNIONE EUROPEA  
Fondo Europeo di Sviluppo Regionale



*Ministero dell'Istruzione,  
dell'Università e della Ricerca*

